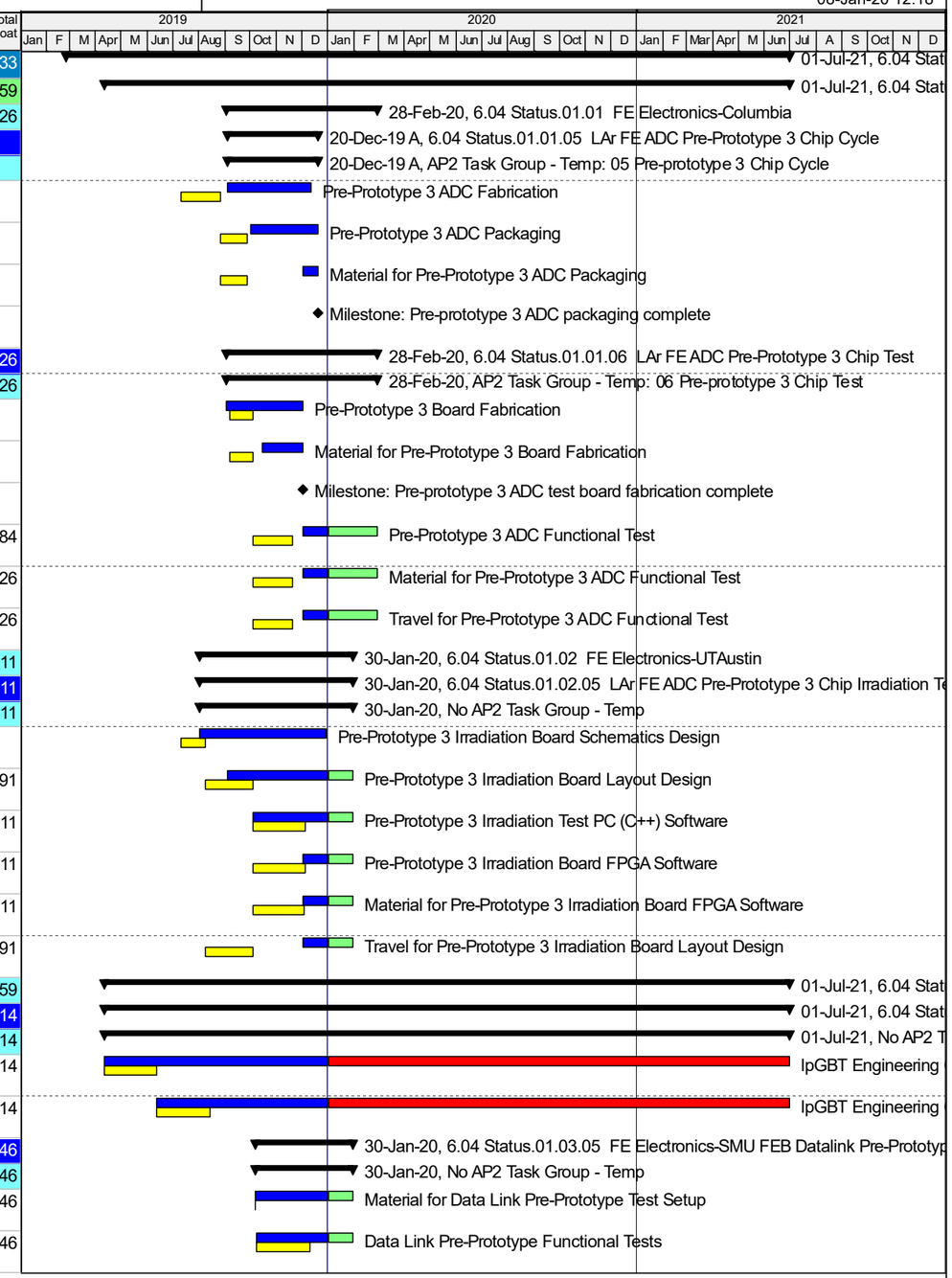
Activity ID	Activity Name	Planned Duration	% Comp	BL Project Start	BL Project Finish	Start	Finish	Total Float
6.04 Status LAr		597		25-Feb-19	03-Dec-20	25-Feb-19 A	01-Jul-21	1833
6.04 Status.01 FE Electronics		564		11-Apr-19	03-Dec-20	11-Apr-19 A	01-Jul-21	59
6.04 Status.01.01 FE Electronics-Columbia		114		11-Jul-19	20-Nov-19	02-Sep-19 A	28-Feb-20	226
6.04 Status.01.01.05 LAr FE ADC Pre-Prototype 3 Chip Cycle		83		11-Jul-19	27-Sep-19	03-Sep-19 A	20-Dec-19 A	
AP2 Task Group - Temp: 05 Pre-prototype 3 Chip Cycle		83		11-Jul-19	27-Sep-19	03-Sep-19 A	20-Dec-19 A	
FEE10310	Pre-Prototype 3 ADC Fabrication	81	100%	11-Jul-19	27-Aug-19	03-Sep-19 A	12-Dec-19 A	
FEE10320	Pre-Prototype 3 ADC Packaging	48	100%	27-Aug-19	27-Sep-19	01-Oct-19 A	20-Dec-19 A	
FEE10320M	Material for Pre-Prototype 3 ADC Packaging	22	100%	27-Aug-19	27-Sep-19	02-Dec-19 A	20-Dec-19 A	
FEE10330	Milestone: Pre-prototype 3 ADC packaging complete	0	100%		27-Sep-19		20-Dec-19 A	
6.04 Status.01.01.06 LAr FE ADC Pre-Prototype 3 Chip Test		114		06-Sep-1	20-Nov-19	02-Sep-19 A	28-Feb-20	226
AP2 Task Group - Temp: 06 Pre-prototype 3 Chip Test		114		06-Sep-1	20-Nov-19	02-Sep-19 A	28-Feb-20	226
FEE10350	Pre-Prototype 3 Board Fabrication	82	100%	06-Sep-19	04-Oct-19	02-Sep-19 A	02-Dec-19 A	
FEE10350M	Material for Pre-Prototype 3 Board Fabrication	52	100%	06-Sep-19	04-Oct-19	15-Oct-19 A	02-Dec-19 A	
FEE10355	Milestone: Pre-prototype 3 ADC test board fabrication complete	0	100%		04-Oct-19		02-Dec-19 A	
FEE10360	Pre-Prototype 3 ADC Functional Test	32	5%	04-Oct-19	20-Nov-19	02-Dec-19 A	28-Feb-20	184
FEE10360M	Material for Pre-Prototype 3 ADC Functional Test	32	5%	04-Oct-19	20-Nov-19	02-Dec-19 A	28-Feb-20	226
FEE10360T	Travel for Pre-Prototype 3 ADC Functional Test	32	5%	04-Oct-19	20-Nov-19	02-Dec-19 A	28-Feb-20	226
6.04 Status.01.02 FE Electronics-UTAustin		167		11-Jul-19	05-Dec-19	01-Aug-19 A	30-Jan-20	211
6.04 Status.01.02.05 LAr FE ADC Pre-Prototype 3 Chip Irradiation Test		167		11-Jul-19	05-Dec-19	01-Aug-19 A	30-Jan-20	211
No AP2 Task Group - Temp		167		11-Jul-19	05-Dec-19	01-Aug-19 A	30-Jan-20	211
FEE20290	Pre-Prototype 3 Irradiation Board Schematics Design	125	100%	11-Jul-19	08-Aug-19	01-Aug-19 A	30-Dec-19 A	
FEE20300	Pre-Prototype 3 Irradiation Board Layout Design	103	70%	08-Aug-19	04-Oct-19	03-Sep-19 A	30-Jan-20	191
FEE20330	Pre-Prototype 3 Irradiation Test PC (C++) Software	100	50%	04-Oct-19	05-Dec-19	04-Oct-19 A	30-Jan-20	211
FEE20320	Pre-Prototype 3 Irradiation Board FPGA Software	42	20%	04-Oct-19	05-Dec-19	02-Dec-19 A	30-Jan-20	211
FEE20320M	Material for Pre-Prototype 3 Irradiation Board FPGA Software	41	20%	04-Oct-19	04-Dec-19	02-Dec-19 A	30-Jan-20	211
FEE20300T	Travel for Pre-Prototype 3 Irradiation Board Layout Design	40	50%	08-Aug-19	04-Oct-19	02-Dec-19 A	30-Jan-20	191
6.04 Status.01.03 FE Electronics-SMU		564		11-Apr-19	03-Dec-20	11-Apr-19 A	01-Jul-21	59
6.04 Status.01.03.02 FE Electronics-SMU lpGBT Engineering Chip		564		11-Apr-19	14-Aug-19	11-Apr-19 A	01-Jul-21	-114
No AP2 Task Group - Temp		564		11-Apr-19	14-Aug-19	11-Apr-19 A	01-Jul-21	-114
FEE30180	lpGBT Engineering Chip Design Work, Implement Necessary Changes	564	95%	11-Apr-19	11-Jun-19	11-Apr-19 A	01-Jul-21	-114
FEE30190	lpGBT Engineering Chip Design Work, Overall Integration and Prepare for Submission	521	70%	12-Jun-19	14-Aug-19	12-Jun-19 A	01-Jul-21	-114
6.04 Status.01.03.05 FE Electronics-SMU FEB Datalink Pre-Prototype		59		07-Oct-19	10-Dec-19	07-Oct-19 A	30-Jan-20	246
No AP2 Task Group - Temp		59		07-Oct-19	10-Dec-19	07-Oct-19 A	30-Jan-20	246
FEE30720M	Material for Data Link Pre-Prototype Test Setup	59	50%	07-Oct-19	07-Oct-19	07-Oct-19 A	30-Jan-20	246
FEE30730	Data Link Pre-Prototype Functional Tests	58	70%	08-Oct-19	10-Dec-19	08-Oct-19 A	30-Jan-20	246



Primary Baseline | Remaining Work | Milestone
Actual Work | Critical Remaining Work | Summary

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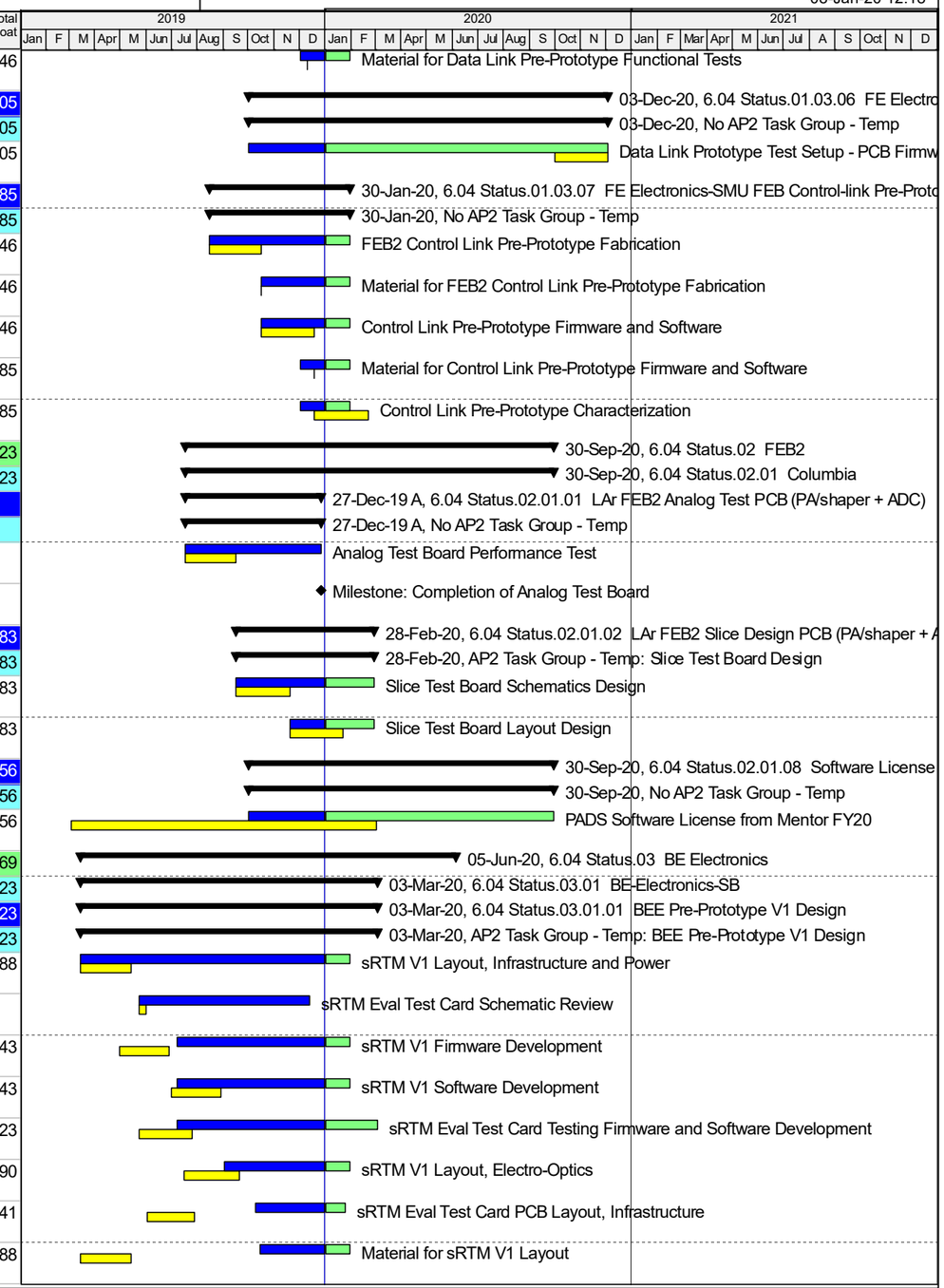
Activity ID	Activity Name	Planned Duration	% Comp	BL Project Start	BL Project Finish	Start	Finish	Total Float
FEE30730M	Material for Data Link Pre-Prototype Functional Tests	1	50%	10-Dec-19	10-Dec-19	02-Dec-19 A	30-Jan-20	246
6.04 Status.01.03.06	**FE Electronics-SMU FEB Datalink Prototype**	**297**		**02-Oct-20**	**03-Dec-20**	**02-Oct-19 A**	**03-Dec-20**	**205**
No AP2 Task Group - Temp		**297**		**02-Oct-20**	**03-Dec-20**	**02-Oct-19 A**	**03-Dec-20**	**205**
FEE30820	Data Link Prototype Test Setup - PCB Firmware Plus Software	297	5%	02-Oct-20	03-Dec-20	02-Oct-19 A	03-Dec-20	205
6.04 Status.01.03.07	**FE Electronics-SMU FEB Control-link Pre-Prototype**	**138**		**15-Aug-1**	**21-Feb-20**	**15-Aug-19 A**	**30-Jan-20**	**285**
No AP2 Task Group - Temp		**138**		**15-Aug-1**	**21-Feb-20**	**15-Aug-19 A**	**30-Jan-20**	**285**
FEE30890	FEB2 Control Link Pre-Prototype Fabrication	95	80%	15-Aug-19	16-Oct-19	15-Aug-19 A	30-Jan-20	246
FEE30890M	Material for FEB2 Control Link Pre-Prototype Fabrication	53	80%	16-Oct-19	16-Oct-19	16-Oct-19 A	30-Jan-20	246
FEE30900	Control Link Pre-Prototype Firmware and Software	52	60%	17-Oct-19	19-Dec-19	17-Oct-19 A	30-Jan-20	246
FEE30900M	Material for Control Link Pre-Prototype Firmware and Software	1	40%	18-Dec-19	19-Dec-19	02-Dec-19 A	30-Jan-20	285
FEE30910	Control Link Pre-Prototype Characterization	43	40%	19-Dec-19	21-Feb-20	02-Dec-19 A	30-Jan-20	285
6.04 Status.02 FEB2		**305**		**04-Mar-19**	**02-Mar-20**	**18-Jul-19 A**	**30-Sep-20**	**2023**
6.04 Status.02.01 Columbia		**305**		**04-Mar-19**	**02-Mar-20**	**18-Jul-19 A**	**30-Sep-20**	**2023**
6.04 Status.02.01.01	**LAr FEB2 Analog Test PCB (PA/shaper + ADC)**	**114**		**18-Jul-19**	**16-Sep-19**	**18-Jul-19 A**	**27-Dec-19 A**	
No AP2 Task Group - Temp		**114**		**18-Jul-19**	**16-Sep-19**	**18-Jul-19 A**	**27-Dec-19 A**	
FEB21070	Analog Test Board Performance Test	114	100%	18-Jul-19	16-Sep-19	18-Jul-19 A	27-Dec-19 A	
FEB21080	Milestone: Completion of Analog Test Board	0	100%		16-Sep-19		27-Dec-19 A	
6.04 Status.02.01.02	**LAr FEB2 Slice Design PCB (PA/shaper + ADC + Optics)**	**114**		**16-Sep-1**	**22-Jan-20**	**16-Sep-19 A**	**28-Feb-20**	**183**
AP2 Task Group - Temp: Slice Test Board Design		**114**		**16-Sep-1**	**22-Jan-20**	**16-Sep-19 A**	**28-Feb-20**	**183**
FEB21090	Slice Test Board Schematics Design	95	30%	16-Sep-19	19-Nov-19	16-Sep-19 A	28-Feb-20	183
FEB21100	Slice Test Board Layout Design	69	20%	19-Nov-19	22-Jan-20	19-Nov-19 A	28-Feb-20	183
6.04 Status.02.01.08	**Software License**	**254**		**04-Mar-19**	**02-Mar-20**	**01-Oct-19 A**	**30-Sep-20**	**256**
No AP2 Task Group - Temp		**254**		**04-Mar-19**	**02-Mar-20**	**01-Oct-19 A**	**30-Sep-20**	**256**
FEB21810	PADS Software License from Mentor FY20	254	0%	04-Mar-19	02-Mar-20	01-Oct-19 A	30-Sep-20	256
6.04 Status.03 BE Electronics		**312**		**15-Mar-19**	**27-May-20**	**15-Mar-19 A**	**05-Jun-20**	**169**
6.04 Status.03.01 BE-Electronics-SB		**244**		**15-Mar-19**	**31-Oct-19**	**15-Mar-19 A**	**03-Mar-20**	**223**
6.04 Status.03.01.01	**BEE Pre-Prototype V1 Design**	**244**		**15-Mar-19**	**31-Oct-19**	**15-Mar-19 A**	**03-Mar-20**	**223**
AP2 Task Group - Temp: BEE Pre-Prototype V1 Design		**244**		**15-Mar-19**	**31-Oct-19**	**15-Mar-19 A**	**03-Mar-20**	**223**
BEE10125	sRTM V1 Layout, Infrastructure and Power	182	40%	15-Mar-19	14-May-19	15-Mar-19 A	30-Jan-20	188
BEE10170	sRTM Eval Test Card Schematic Review	142	100%	24-May-19	31-May-19	24-May-19 A	13-Dec-19 A	
BEE10105	sRTM V1 Firmware Development	103	15%	30-Apr-19	28-Jun-19	08-Jul-19 A	30-Jan-20	243
BEE10110	sRTM V1 Software Development	103	15%	01-Jul-19	29-Aug-19	08-Jul-19 A	30-Jan-20	243
BEE10180	sRTM Eval Test Card Testing Firmware and Software Development	122	40%	24-May-19	26-Jul-19	08-Jul-19 A	03-Mar-20	223
BEE10135	sRTM V1 Layout, Electro-Optics	62	10%	16-Jul-19	20-Sep-19	03-Sep-19 A	30-Jan-20	190
BEE10190	sRTM Eval Test Card PCB Layout, Infrastructure	98	20%	03-Jun-19	29-Jul-19	10-Oct-19 A	24-Jan-20	141
BEE10125M	Material for sRTM V1 Layout	34	15%	15-Mar-19	14-May-19	15-Oct-19 A	30-Jan-20	188



Primary Baseline | Remaining Work | Milestone
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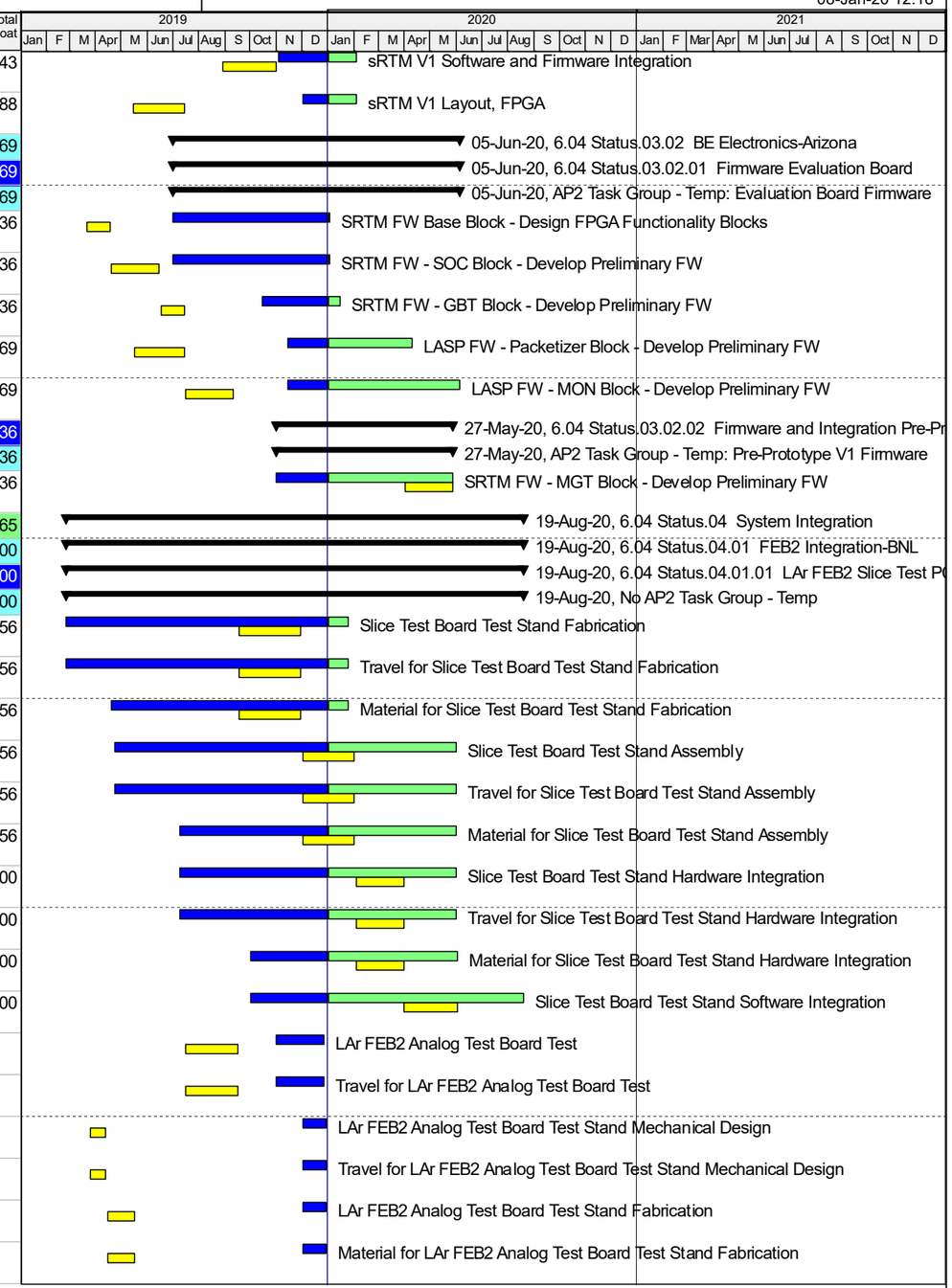
Activity ID	Activity Name	Planned Duration	% Comp	BL Project Start	BL Project Finish	Start	Finish	Total Float
BEE10120	sRTM V1 Software and Firmware Integration	63	10%	29-Aug-19	31-Oct-19	04-Nov-19 A	03-Feb-20	243
BEE10130	sRTM V1 Layout, FPGA	42	10%	15-May-19	15-Jul-19	03-Dec-19 A	03-Feb-20	188
6.04 Status.03.02 BE Electronics-Arizona		**237**		**22-Mar-19**	**27-May-20**	**01-Jul-19 A**	**05-Jun-20**	**169**
6.04 Status.03.02.01 Firmware Evaluation Board		**237**		**22-Mar-19**	**10-Sep-19**	**01-Jul-19 A**	**05-Jun-20**	**169**
AP2 Task Group - Temp: Evaluation Board Firmware		**237**		**22-Mar-19**	**10-Sep-19**	**01-Jul-19 A**	**05-Jun-20**	**169**
BEE12080	SRTM FW Base Block - Design FPGA Functionality Blocks	128	60%	22-Mar-19	18-Apr-19	01-Jul-19 A	02-Jan-20	136
BEE12085	SRTM FW - SOC Block - Develop Preliminary FW	128	80%	19-Apr-19	14-Jun-19	01-Jul-19 A	02-Jan-20	136
BEE12090	SRTM FW - GBT Block - Develop Preliminary FW	64	80%	17-Jun-19	15-Jul-19	15-Oct-19 A	15-Jan-20	136
BEE12110	LASP FW - Packetizer Block - Develop Preliminary FW	101	20%	17-May-19	15-Jul-19	15-Nov-19 A	09-Apr-20	169
BEE12112	LASP FW - MON Block - Develop Preliminary FW	141	10%	16-Jul-19	10-Sep-19	15-Nov-19 A	05-Jun-20	169
6.04 Status.03.02.02 Firmware and Integration Pre-Prototype V1		**144**		**01-Apr-20**	**27-May-20**	**01-Nov-19 A**	**27-May-20**	**136**
AP2 Task Group - Temp: Pre-Prototype V1 Firmware		**144**		**01-Apr-20**	**27-May-20**	**01-Nov-19 A**	**27-May-20**	**136**
BEE12120	SRTM FW - MGT Block - Develop Preliminary FW	144	10%	01-Apr-20	27-May-20	01-Nov-19 A	27-May-20	136
6.04 Status.04 System Integration		**378**		**25-Feb-19**	**07-Oct-20**	**25-Feb-19 A**	**19-Aug-20**	**265**
6.04 Status.04.01 FEB2 Integration-BNL		**378**		**25-Feb-19**	**02-Jun-20**	**25-Feb-19 A**	**19-Aug-20**	**200**
6.04 Status.04.01.01 LAr FEB2 Slice Test PCB Integration		**378**		**25-Feb-19**	**02-Jun-20**	**25-Feb-19 A**	**19-Aug-20**	**200**
No AP2 Task Group - Temp		**378**		**25-Feb-19**	**02-Jun-20**	**25-Feb-19 A**	**19-Aug-20**	**200**
SYS460030	Slice Test Board Test Stand Fabrication	210	60%	17-Sep-19	29-Nov-19	25-Feb-19 A	24-Jan-20	256
SYS460030T	Travel for Slice Test Board Test Stand Fabrication	210	30%	17-Sep-19	29-Nov-19	25-Feb-19 A	24-Jan-20	256
SYS460030M	Material for Slice Test Board Test Stand Fabrication	171	30%	17-Sep-19	29-Nov-19	19-Apr-19 A	24-Jan-20	256
SYS460040	Slice Test Board Test Stand Assembly	281	5%	02-Dec-19	31-Jan-20	23-Apr-19 A	01-Jun-20	256
SYS460040T	Travel for Slice Test Board Test Stand Assembly	281	5%	02-Dec-19	31-Jan-20	23-Apr-19 A	01-Jun-20	256
SYS460040M	Material for Slice Test Board Test Stand Assembly	228	5%	02-Dec-19	31-Jan-20	09-Jul-19 A	01-Jun-20	256
SYS460060	Slice Test Board Test Stand Hardware Integration	227	5%	03-Feb-20	30-Mar-20	10-Jul-19 A	01-Jun-20	200
SYS460060T	Travel for Slice Test Board Test Stand Hardware Integration	227	5%	03-Feb-20	30-Mar-20	10-Jul-19 A	01-Jun-20	200
SYS460060M	Material for Slice Test Board Test Stand Hardware Integration	170	5%	03-Feb-20	30-Mar-20	01-Oct-19 A	02-Jun-20	200
SYS460070	Slice Test Board Test Stand Software Integration	225	5%	31-Mar-20	02-Jun-20	01-Oct-19 A	19-Aug-20	200
SYS460028	LAr FEB2 Analog Test Board Test	35	100%	17-Jul-19	16-Sep-19	01-Nov-19 A	27-Dec-19 A	
SYS460028T	Travel for LAr FEB2 Analog Test Board Test	35	100%	17-Jul-19	16-Sep-19	01-Nov-19 A	27-Dec-19 A	
SYS460022	LAr FEB2 Analog Test Board Test Stand Mechanical Design	15	100%	25-Mar-19	12-Apr-19	02-Dec-19 A	30-Dec-19 A	
SYS460022T	Travel for LAr FEB2 Analog Test Board Test Stand Mechanical Design	15	100%	25-Mar-19	12-Apr-19	02-Dec-19 A	30-Dec-19 A	
SYS460023	LAr FEB2 Analog Test Board Test Stand Fabrication	25	100%	15-Apr-19	17-May-19	02-Dec-19 A	30-Dec-19 A	
SYS460023M	Material for LAr FEB2 Analog Test Board Test Stand Fabrication	25	100%	15-Apr-19	17-May-19	02-Dec-19 A	30-Dec-19 A	



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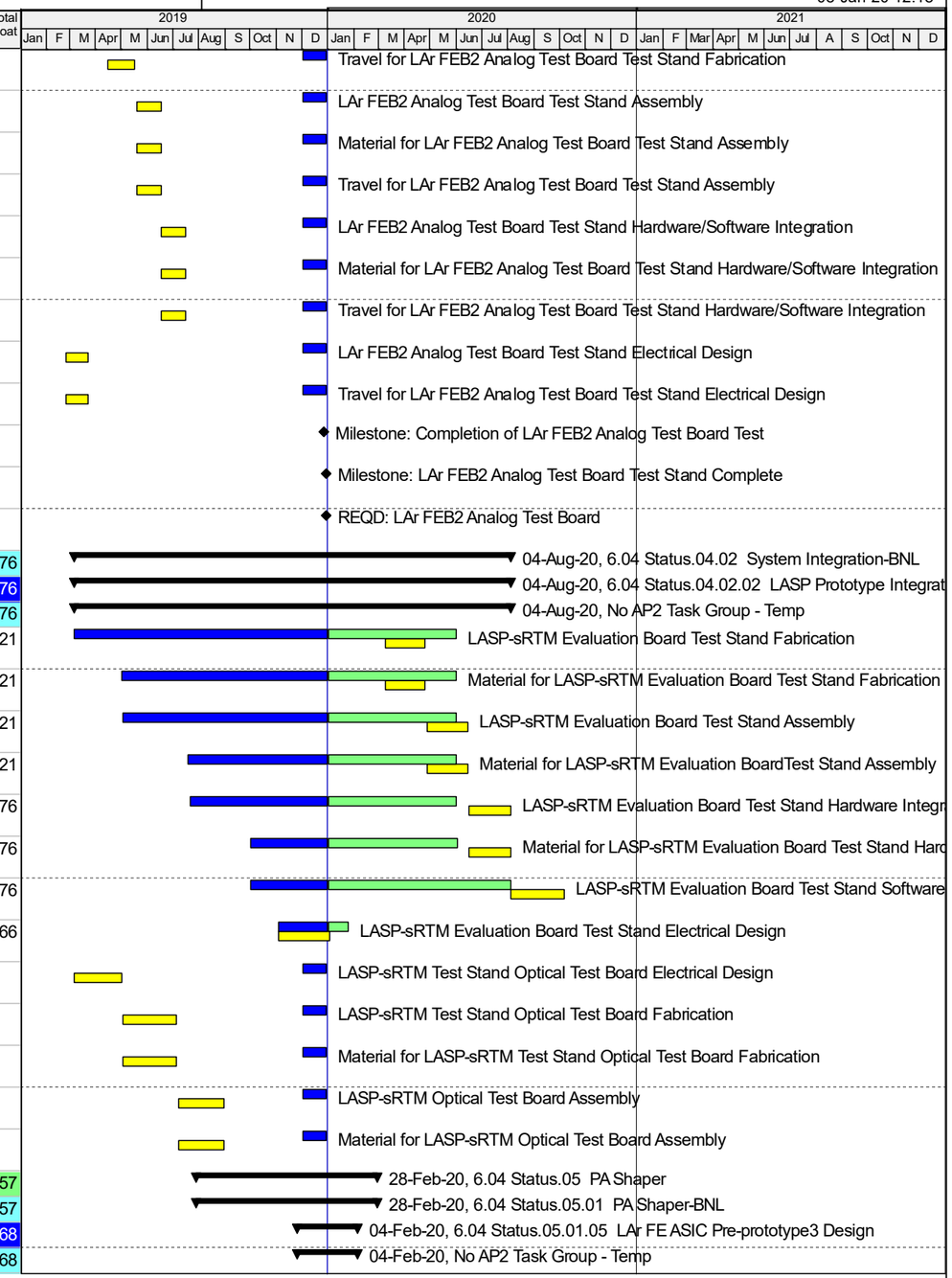
Activity ID	Activity Name	Planned Duration	% Comp	BL Project Start	BL Project Finish	Start	Finish	Total Float
SYS460023T	Travel for LAr FEB2 Analog Test Board Test Stand Fabrication	25	100%	15-Apr-19	17-May-19	02-Dec-19 A	30-Dec-19 A	
SYS460024	LAr FEB2 Analog Test Board Test Stand Assembly	20	100%	20-May-19	17-Jun-19	02-Dec-19 A	30-Dec-19 A	
SYS460024M	Material for LAr FEB2 Analog Test Board Test Stand Assembly	20	100%	20-May-19	17-Jun-19	02-Dec-19 A	30-Dec-19 A	
SYS460024T	Travel for LAr FEB2 Analog Test Board Test Stand Assembly	20	100%	20-May-19	17-Jun-19	02-Dec-19 A	30-Dec-19 A	
SYS460026	LAr FEB2 Analog Test Board Test Stand Hardware/Software Integration	20	100%	18-Jun-19	16-Jul-19	02-Dec-19 A	30-Dec-19 A	
SYS460026M	Material for LAr FEB2 Analog Test Board Test Stand Hardware/Software Integration	20	100%	18-Jun-19	16-Jul-19	02-Dec-19 A	30-Dec-19 A	
SYS460026T	Travel for LAr FEB2 Analog Test Board Test Stand Hardware/Software Integration	20	100%	18-Jun-19	16-Jul-19	02-Dec-19 A	30-Dec-19 A	
SYS460021	LAr FEB2 Analog Test Board Test Stand Electrical Design	20	100%	25-Feb-19	22-Mar-19	02-Dec-19 A	30-Dec-19 A	
SYS460021T	Travel for LAr FEB2 Analog Test Board Test Stand Electrical Design	20	100%	25-Feb-19	22-Mar-19	02-Dec-19 A	30-Dec-19 A	
SYS460029	Milestone: Completion of LAr FEB2 Analog Test Board Test	0	100%		16-Sep-19		27-Dec-19 A	
SYS460025	Milestone: LAr FEB2 Analog Test Board Test Stand Complete	0	100%		17-Jun-19		30-Dec-19 A	
SYS460027R	REQD: LAr FEB2 Analog Test Board	0	100%	17-Jul-19		30-Dec-19 A		
6.04 Status.04.02 System Integration-BNL		359		07-Mar-19	07-Oct-20	07-Mar-19 A	04-Aug-20	276
6.04 Status.04.02.02 LASP Prototype Integration		359		07-Mar-19	07-Oct-20	07-Mar-19 A	04-Aug-20	276
No AP2 Task Group - Temp		359		07-Mar-19	07-Oct-20	07-Mar-19 A	04-Aug-20	276
SYS460530	LASP-sRTM Evaluation Board Test Stand Fabrication	314	10%	09-Mar-20	24-Apr-20	07-Mar-19 A	01-Jun-20	321
SYS460530M	Material for LASP-sRTM Evaluation Board Test Stand Fabrication	274	10%	09-Mar-20	24-Apr-20	02-May-19 A	01-Jun-20	321
SYS460540	LASP-sRTM Evaluation Board Test Stand Assembly	273	5%	27-Apr-20	15-Jun-20	03-May-19 A	01-Jun-20	321
SYS460540M	Material for LASP-sRTM Evaluation BoardTest Stand Assembly	220	5%	27-Apr-20	15-Jun-20	19-Jul-19 A	01-Jun-20	321
SYS460560	LASP-sRTM Evaluation Board Test Stand Hardware Integration	219	5%	16-Jun-20	04-Aug-20	22-Jul-19 A	01-Jun-20	276
SYS460560M	Material for LASP-sRTM Evaluation Board Test Stand Hardware Integration	170	5%	16-Jun-20	04-Aug-20	01-Oct-19 A	02-Jun-20	276
SYS460570	LASP-sRTM Evaluation Board Test Stand Software Integration	214	5%	05-Aug-20	07-Oct-20	01-Oct-19 A	04-Aug-20	276
SYS460525	LASP-sRTM Evaluation Board Test Stand Electrical Design	39	60%	04-Nov-19	03-Jan-20	04-Nov-19 A	24-Jan-20	366
SYS460521	LASP-sRTM Test Stand Optical Test Board Electrical Design	41	100%	07-Mar-19	02-May-19	02-Dec-19 A	30-Dec-19 A	
SYS460522	LASP-sRTM Test Stand Optical Test Board Fabrication	44	100%	03-May-19	05-Jul-19	02-Dec-19 A	30-Dec-19 A	
SYS460522M	Material for LASP-sRTM Test Stand Optical Test Board Fabrication	44	100%	03-May-19	05-Jul-19	02-Dec-19 A	30-Dec-19 A	
SYS460523	LASP-sRTM Optical Test Board Assembly	40	100%	08-Jul-19	30-Aug-19	02-Dec-19 A	30-Dec-19 A	
SYS460523M	Material for LASP-sRTM Optical Test Board Assembly	40	100%	08-Jul-19	30-Aug-19	02-Dec-19 A	30-Dec-19 A	
6.04 Status.05 PA Shaper		148		24-May-1	25-Oct-19	29-Jul-19 A	28-Feb-20	-57
6.04 Status.05.01 PA Shaper-BNL		148		24-May-1	25-Oct-19	29-Jul-19 A	28-Feb-20	-57
6.04 Status.05.01.05 LAr FE ASIC Pre-prototype3 Design		48		26-Jul-19	25-Oct-19	25-Nov-19 A	04-Feb-20	-68
No AP2 Task Group - Temp		48		26-Jul-19	25-Oct-19	25-Nov-19 A	04-Feb-20	-68



Primary Baseline | Remaining Work | Milestone
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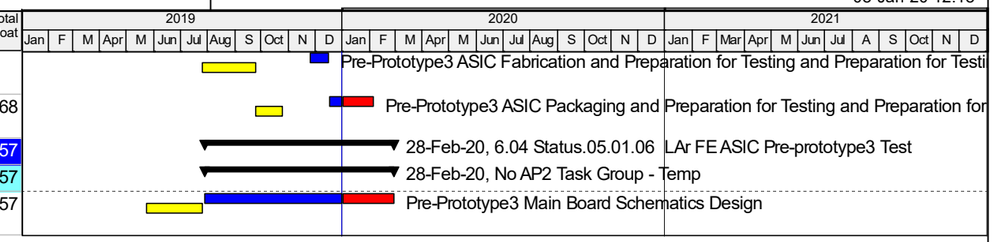
Activity ID	Activity Name	Planned Duration	% Comp	BL Project Start	BL Project Finish	Start	Finish	Total Float
ASIC460310	Pre-Prototype3 ASIC Fabrication and Preparation for Testing and Preparation for Testing	26	100%	26-Jul-19	24-Sep-19	25-Nov-19 A	17-Dec-19 A	
ASIC460320	Pre-Prototype3 ASIC Packaging and Preparation for Testing and Preparation for Testing	22	10%	24-Sep-19	25-Oct-19	18-Dec-19 A	04-Feb-20	-68
6.04 Status.05.01.06	**LAr FE ASIC Pre-prototype3 Test**	148		24-May-1	26-Jul-19	29-Jul-19 A	28-Feb-20	-57
No AP2 Task Group - Temp		148		24-May-1	26-Jul-19	29-Jul-19 A	28-Feb-20	-57
ASIC460330	Pre-Prototype3 Main Board Schematics Design	148	80%	24-May-19	26-Jul-19	29-Jul-19 A	28-Feb-20	-57



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